

Abstract

To enhance the adhesion force between a lead frame and a molding compound of a surface mount semiconductor device, a lead frame having two opposite sides, with at least one tilt flap for locking a molding compound extending from one side and a reduced portion of the lead frame extending from the opposite side, and a surface mount semiconductor device having the same, are disclosed. The at least one tilt flap and the reduced portion are formed on the lead frame such that the adhesion force between the lead frame and the molding compound is enhanced.